HX313C9F/8

8GB 1G x 64-Bit DDR3-1333
CL9 240-Pin DIMM

SPECIFICATIONS

CL(IDD)	9 cycles
Row Cycle Time (tRCmin)	49.125ns (min.)
Refresh to Active/Refresh Command Time (tRFCmin)	260ns (min.)
Row Active Time (tRASmin)	36ns (min.)
Maximum Operating Power	TBD W*
UL Rating	94 V - 0
Operating Temperature	0° C to 85° C
Storage Temperature	-55° C to $+100^o$ C

*Power will vary depending on the SDRAM used.

DESCRIPTION

HyperX HX313C9F/8 is a 1G x 64-bit (8GB) DDR3-1333 CL9 SDRAM (Synchronous DRAM) 2Rx8 memory module, based on sixteen 512M x 8-bit DDR3 FBGA components. This module has been tested to run at DDR3-1333 at latency timing 9-9-9 at 1.5V. The JEDEC standard electrical and mechanical specifications are as follows:
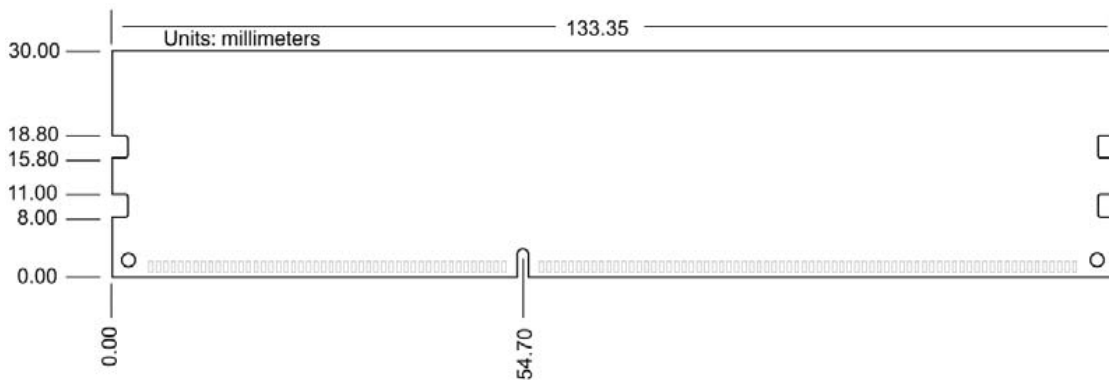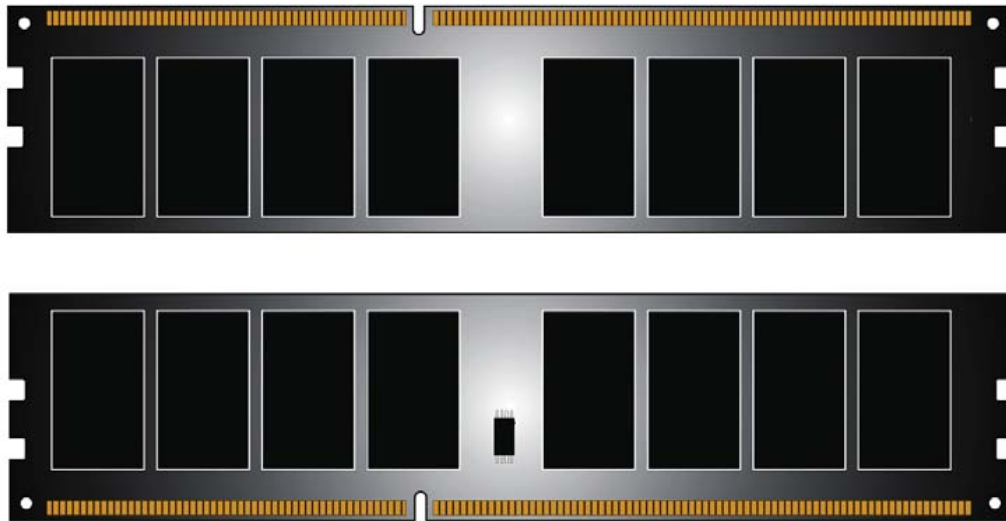
FEATURES

- JEDEC standard 1.5V (1.425V ~1.575V) Power Supply

- VDDQ = 1.5V (1.425V ~ 1.575V)

- 667MHz fCK for 1333Mb/sec/pin

- 8 independent internal bank

- Programmable CAS Latency: 9, 8, 7, 6

- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock

- 8-bit pre-fetch

- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]

- Bi-directional Differential Data Strobe

- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)

- On Die Termination using ODT pin

- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE $\leq$ 95°C

- Asynchronous Reset

- Height 1.291" (32.80mm) w/heatsink, double sided component

MODULE WITH HEAT SPREADER

7.08 mm

133.35 mm

32.8 mm

FURY HYPERX

MODULE DIMENSIONS

Units: millimeters   133.35

30.00

18.80
15.80

11.00
8.00

0.00

0.00   54.70

FOR MORE INFORMATION, GO TO WWW.KINGSTON.COM/HYPERX